

TO-247-2 Silicon Carbide Schottky Diode

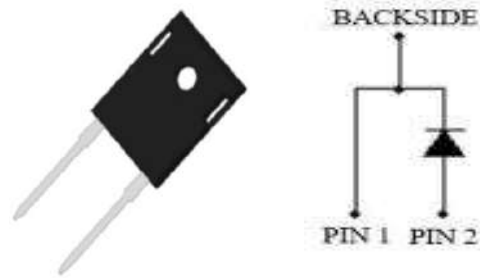
SiC Diode 1200V 20A 106nC

General Description

This product family offers state of the art performance. It is designed for high frequency applications here high efficiency and high reliability are required.

Features

- Zero Forward/Reverse Recovery Current
- High Blocking Voltage
- High Frequency Operation
- Positive Temperature Coefficient on VF
- Temperature Independent Switching Behavior



**TO-247-2
Pin definition**

Applications

- Motor Drives
- Solar
- AC/DC converters
- DC/DC converters
- Uninterruptable power supplies

Benefits

- Higher System Efficiency
- Parallel Device Convenience without thermal runaway
- Higher Temperature Application
- No Switching loss
- Hard Switching & Higher Reliability
- Environmental Protection

Key performance parameters

| Type | V_R | I_F $T_C=150^\circ C$ | Q_C |
|---------------|--------|----------------------------|--------|
| KWSC 120C20T2 | 1200 V | 20A | 106 nC |

Caution: This device is sensitive to electrostatic discharge .Users should follow ESD handling procedures.

Maximum Ratings

$T_C=25^{\circ}\text{C}$, unless otherwise specified

| Parameter | Symbol | Value | Unit |
|---------------------------------|-----------|-------|------|
| Peak Repetitive Reverse Voltage | V_{RRM} | 1200 | V |
| Peak Reverse Surge Voltage | V_{RSM} | 1200 | V |
| DC Blocking Voltage | V_R | 1200 | V |

Maximum Ratings

$T_C=25^{\circ}\text{C}$, unless otherwise specified

| Symbol | Parameter | Test conditions | Value | Unit |
|---------------|--------------------------------------|---|------------|----------------------|
| V_{RRM} | Repetitive peak reverse voltage | | 1200 | V |
| V_{RSM} | Surge peak reverse voltage | | 1200 | V |
| I_F | Continuous forward current | $T_C=25^{\circ}\text{C}$ $T_C=150^{\circ}\text{C}$ | 61 20 | A |
| I_{FSM} | Non-Repetitive forward surge current | $T_C=25^{\circ}\text{C}$, $t_p=10\text{ms}$, Half Sine Wave | 185 | A |
| $\int i^2 dt$ | $i^2 t$ value | $T_C=25^{\circ}\text{C}$, $t_p=10\text{ms}$ | 171 | A^2S |
| P_{tot} | Power dissipation | $T_C=25^{\circ}\text{C}$ $T_C=110^{\circ}\text{C}$ | 267 116 | W |
| T_j | Operating junction temperature | | -55~175 | $^{\circ}\text{C}$ |
| T_{stg} | Storage temperature | | -55~175 | $^{\circ}\text{C}$ |

Thermal Resistance

| Parameter | Symbol | Typ. | Max | Unit |
|-----------------------------------|------------|------|-----|------|
| Thermal resistance, junction-case | R_{thJC} | 0.56 | | °C/W |

Electrical Characteristic

$T_C = 25^\circ\text{C}$, unless otherwise specified

| Symbol | Parameter | Test conditions | Value | | | Unit |
|----------|-----------------------|---|-------|--------------|--------------|---------------|
| | | | Min. | Typ. | Max. | |
| V_{DC} | DC blocking voltage | $T_j = 25^\circ\text{C}$ | 1200 | | | V |
| V_F | Diode forward voltage | $I_F = 20\text{A}, T_j = 25^\circ\text{C}$ $I_F = 20\text{A}, T_j = 175^\circ\text{C}$ | | 1.39 1.98 | 1.70 2.85 | V |
| I_R | Reverse current | $V_R = 1200\text{V}, T_j = 25^\circ\text{C}$ $V_R = 1200\text{V}, T_j = 175^\circ\text{C}$ | | 0.5 9 | 200 400 | μA |

AC Characteristic

| Symbol | Parameter | Test conditions | Value | | | Unit |
|--------|---------------------------|--|-------|------------------|------|---------------|
| | | | Min. | Typ. | Max. | |
| Q_C | Total capacitive charge | $V_R = 800\text{V}, T_j = 25^\circ\text{C}$ $Q_C = \int_0^V R C(V) dV$ | | 106 | | nC |
| C | Total capacitance | $V_R = 1\text{V}, f = 1\text{MHz}$ $V_R = 400\text{V}, f = 1\text{MHz}$ $V_R = 800\text{V}, f = 1\text{MHz}$ | | 1144 99 74 | | pF |
| E_C | Capacitance stored energy | $V_R = 800\text{V}$ | | 30 | | μJ |

Typical Characteristics

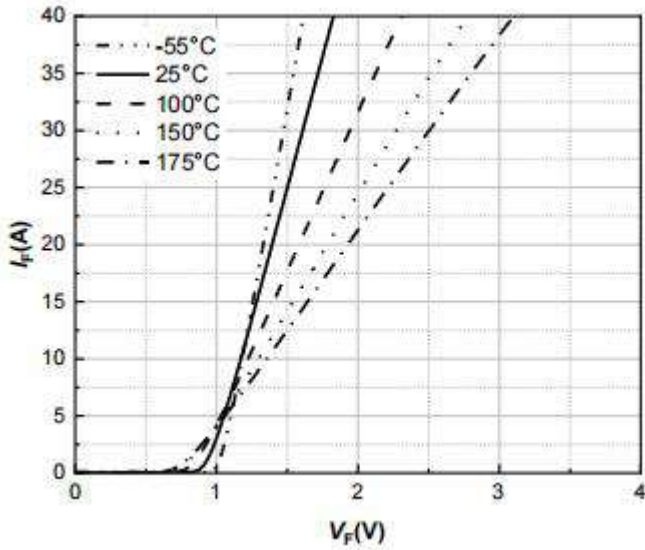


Figure 1. Typical forward characteristics

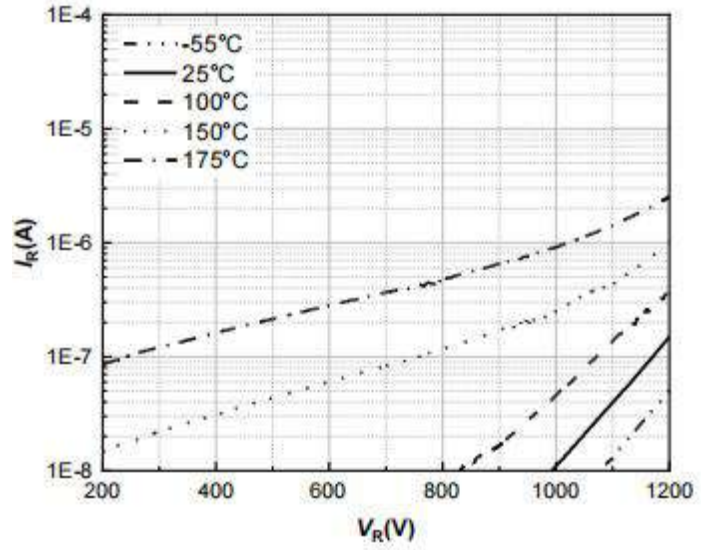


Figure 2. Typical reverse current as function of reverse voltage

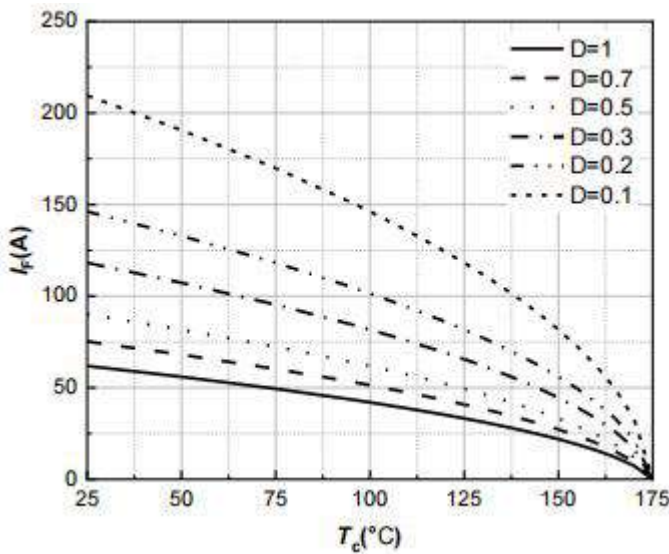


Figure 3. Diode forward current as function of temperature, D=duty cycle

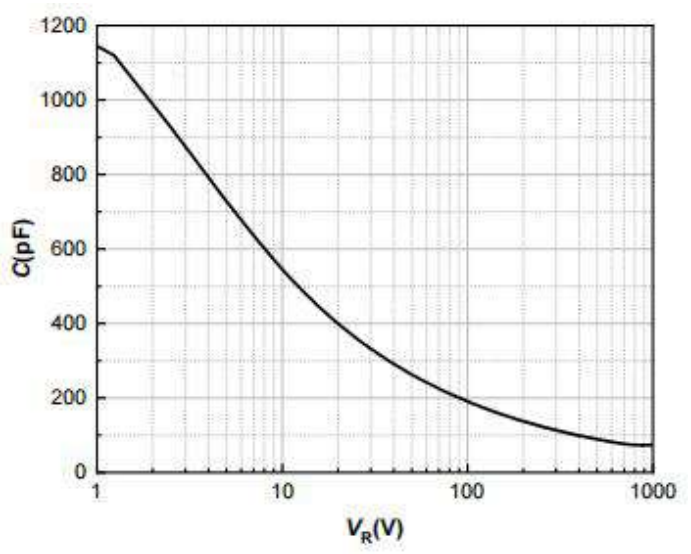


Figure 4. Typical capacitance as function of reverse voltage, $C=f(V_R)$; $T_j=25^\circ\text{C}$; $f=1\text{ MHz}$

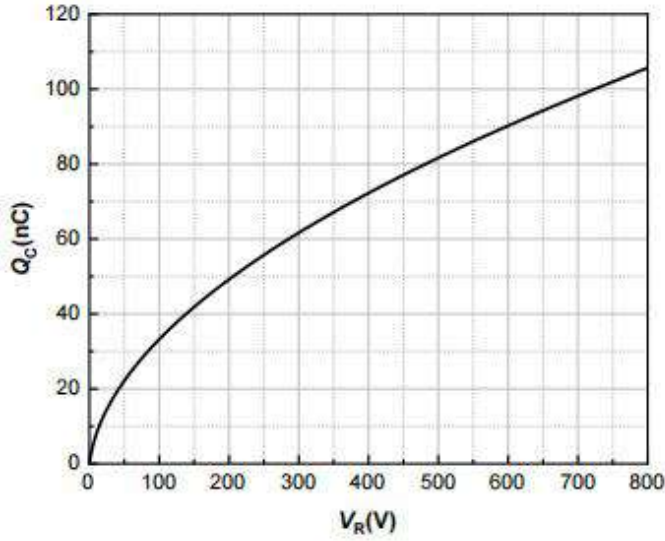


Figure 5. Typical reverse charge as function of reverse voltage

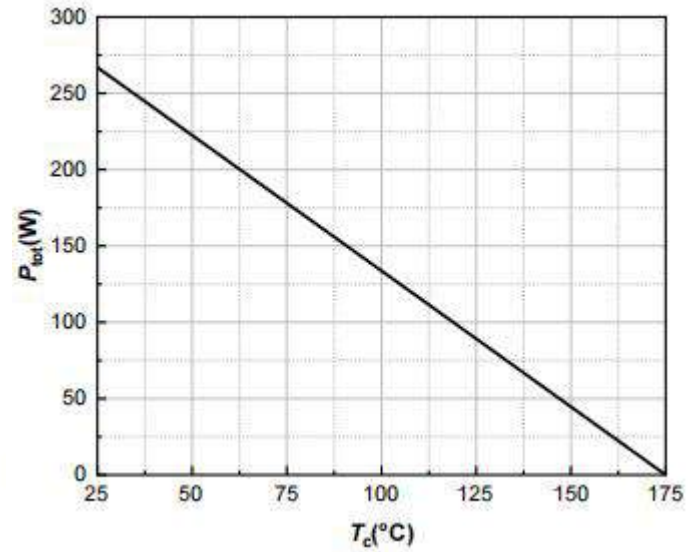


Figure 6. Power dissipation as function of case temperature

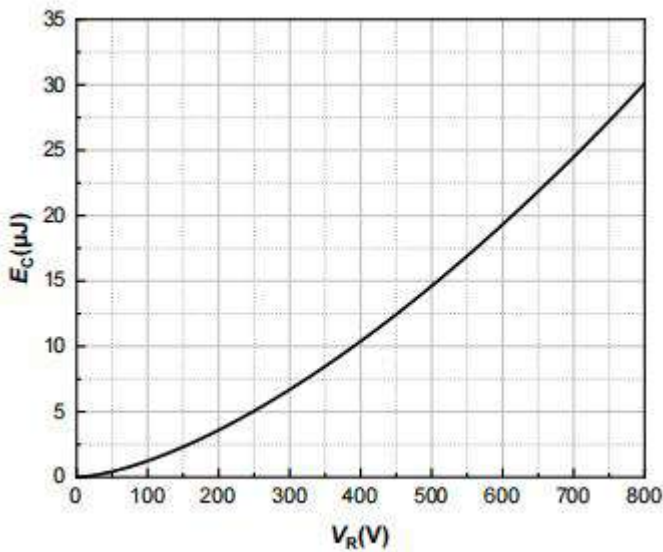


Figure 7. Capacitance stored energy

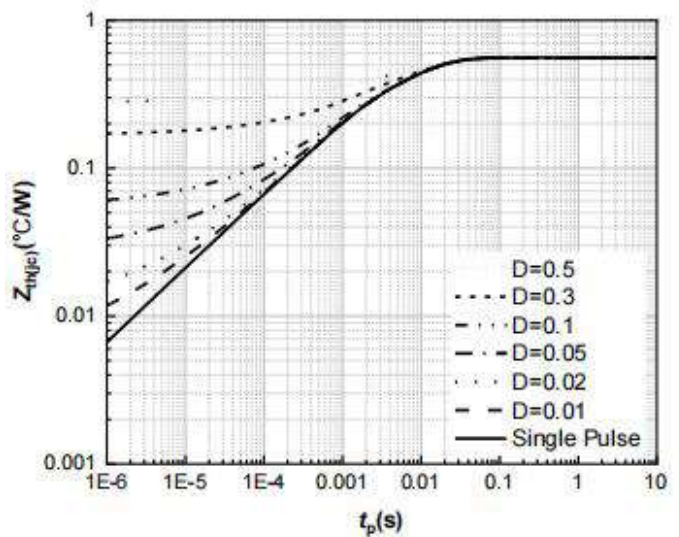
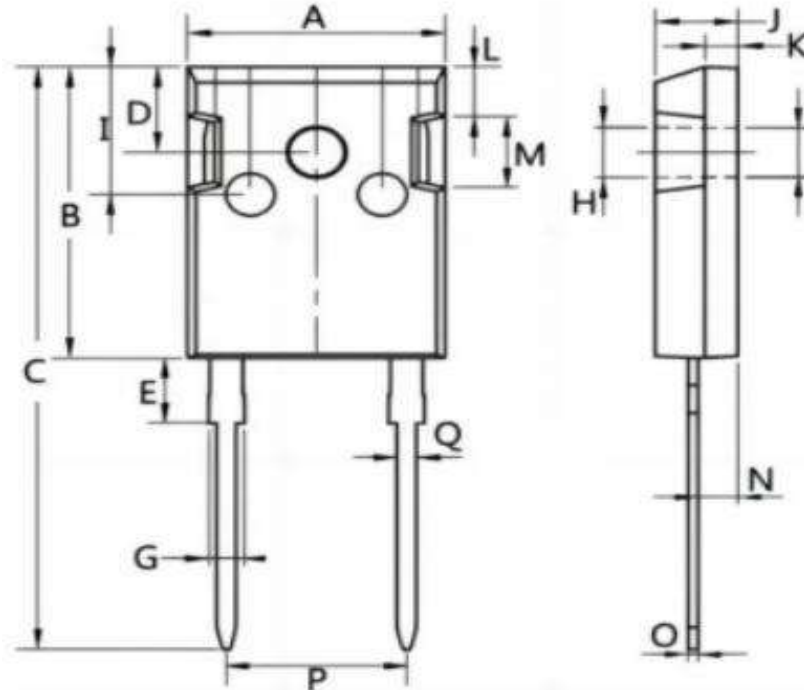


Figure 8. Max. transient thermal impedance, $Z_{th(jc)} = f(t_p)$, parameter: $D = t_p/T$

Package Outline Dimensions

Package Outline: TO-247-2



| Dim. | Min. | Max. |
|------------------------------|----------|-------|
| A | 15.51 | 15.71 |
| B | 20.40 | 20.50 |
| C | 40.5 | 42 |
| D | 5.80 | 6.15 |
| E | 4.25 | 4.40 |
| G | 2.05 | 2.15 |
| H | 3.62 | 4.59 |
| I | 8.15 | 8.60 |
| J | 4.95 | 5.05 |
| K | 1.96 | 1.99 |
| L | 3.65 | 3.8 |
| M | 4.50 | 5.05 |
| N | 2.30 | 2.85 |
| O | 0.59 | 0.61 |
| P | Typ 10.8 | |
| All Dimensions in millimeter | | |